

Abstract

The power semiconductor module (1) comprises several semiconductor components (6, 7, 8), located on a substrate (2). The aim of the invention is to prevent a reduction in the pressure of the substrate against a cooling surface and the resulting loss of cooling arising from deformations. Said aim is achieved, whereby the substrate (2) comprises several substrate regions (3, 4, 5), with one or several connection regions (31, 32), located between substrate regions (3, 4, 5), by means of which the substrate regions (3, 4, 5) are connected such as to move relative to each other.